



## Material Content Data Sheet



<b>Sales Product Name</b>		IPB042N10N3 G		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001163782						
<b>Package</b>		PG-TO263-3-2		<b>Weight*</b>		1562.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.861	0.57	0.57	5671	5671
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		195	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	copper	7440-50-8	304.026	19.46	19.49	194566	194819
wire	non noble metal	aluminium	7429-90-5	8.750	0.56	0.56	5600	5600
encapsulation	organic material	carbon black	1333-86-4	10.143	0.65		6491	
	plastics	epoxy resin	-	111.572	7.14		71403	
	inorganic material	silicondioxide	60676-86-0	554.481	35.47	43.26	354848	432743
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6180	6180
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	146
solder	noble metal	silver	7440-22-4	0.152	0.01		97	
	non noble metal	tin	7440-31-5	0.122	0.01		78	
	non noble metal	lead	7439-92-1	5.815	0.37	0.39	3722	3897
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		351	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	35.05	35.10	350488	350944
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com